



TBN 2891

December 19, 2005

TO: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Attn: Art Unit 2827 - Examiner David A Zarneke

FROM: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/837,007  
File Date: April 18, 2001  
Inventor: M.S. Lin, et al.  
Examiner: David A Zarneke  
Art Unit: 2891  
Title: A Structure and Manufacturing Method of a Chip Scale  
Package

#### RESPONSE TO OFFICE ACTION

Dear Sir:

The Office Action mailed Nov. 18, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on Dec. 19, 2005.

Signature   
Stephen B. Ackerman, Reg. No. 37,761

Date: Dec. 19, 2005

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.